

N-Channel 100 V (D-S) MOSFET

| PRODUCT SUMMARY | | | |
|-----------------|---------------------------------|------------------------|--------------|
| V_{DS} (V) | $R_{DS(on)}$ (Ω), Typ. | I_D (A) ^a | Q_g (Typ.) |
| 100 | 0.0059 at $V_{GS} = -10$ V | 95 | 24.8 nC |
| | 0.0063 at $V_{GS} = -7.5$ V | 93 | |
| | 0.0083 at $V_{GS} = -4.5$ V | 85 | |

FEATURES

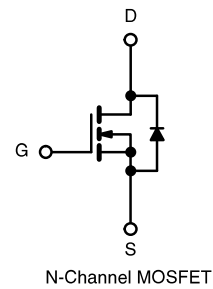
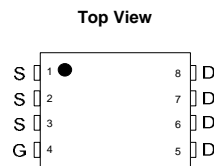
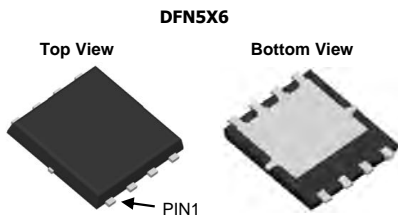
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Fixed Telecom
- DC/DC Converter
- Primary Side Switch



| ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted) | | | |
|---|----------------|---------------|------|
| Parameter | Symbol | Limit | Unit |
| Drain-Source Voltage | V_{DS} | 100 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | |
| Continuous Drain Current ($T_J = 150$ °C) | I_D | $T_C = 25$ °C | A |
| | | $T_C = 70$ °C | |
| | | $T_A = 25$ °C | |
| | | $T_A = 70$ °C | |
| Pulsed Drain Current | I_{DM} | 295 | A |
| Continuous Source-Drain Diode Current | I_S | $T_C = 25$ °C | |
| | | $T_A = 25$ °C | |
| Single Pulse Avalanche Current | I_{AS} | 35 | |
| Single Pulse Avalanche Energy | E_{AS} | 61 | |
| Maximum Power Dissipation | P_D | $T_C = 25$ °C | W |
| | | $T_C = 70$ °C | |
| | | $T_A = 25$ °C | |
| | | $T_A = 70$ °C | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to 150 | °C |
| Soldering Recommendations (Peak Temperature) | | 260 | |

| THERMAL RESISTANCE RATINGS | | | | | |
|---|---------------|------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient ^{b, f} | $t \leq 10$ s | R_{thJA} | 15 | 20 | °C/W |
| Maximum Junction-to-Case (Drain) | Steady State | R_{thJC} | 0.9 | 1.2 | |

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. $t = 10$ s.

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | |
|--|-------------------------|---|------|--------|-----------|----------------------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 100 | | | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | $I_D = 250\text{ }\mu\text{A}$ | | 51 | | mV/ $^\circ\text{C}$ |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | - 6.0 | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 1.2 | | 3.0 | V |
| Gate-Source Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$ | | | 1 | μA |
| | | $V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$ | | | 10 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$ | 30 | | | A |
| Drain-Source On-State Resistance ^a | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 20\text{ A}$ | | 0.0059 | | Ω |
| | | $V_{GS} = 7.5\text{ V}, I_D = 20\text{ A}$ | | 0.0063 | | |
| | | $V_{GS} = 4.5\text{ V}, I_D = 15\text{ A}$ | | 0.0083 | | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = 10\text{ V}, I_D = 20\text{ A}$ | | 73 | | S |
| Dynamic^b | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ | | 2450 | | pF |
| Output Capacitance | C_{oss} | | | 1430 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 80 | | |
| Total Gate Charge | Q_g | $V_{DS} = 50\text{ V}, V_{GS} = 10\text{ V}, I_D = 20\text{ A}$ | | 50.8 | 76 | nC |
| | | $V_{DS} = 50\text{ V}, V_{GS} = 7.5\text{ V}, I_D = 20\text{ A}$ | | 39.2 | 59 | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = 50\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$ | | 24.8 | 37.2 | |
| Gate-Drain Charge | Q_{gd} | | | 8.1 | | |
| Gate Resistance | R_g | $f = 1\text{ MHz}$ | 0.4 | 2.0 | 4.0 | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 50\text{ V}, R_L = 2.5\text{ }\Omega$ $I_D \cong 20\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$ | | 11 | 22 | ns |
| Rise Time | t_r | | | 9 | 18 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 38 | 70 | |
| Fall Time | t_f | | | 11 | 22 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 50\text{ V}, R_L = 2.5\text{ }\Omega$ $I_D \cong 20\text{ A}, V_{GEN} = 7.5\text{ V}, R_g = 1\text{ }\Omega$ | | 15 | 30 | |
| Rise Time | t_r | | | 14 | 28 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 35 | 70 | |
| Fall Time | t_f | | | 10 | 20 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I_S | $T_C = 25\text{ }^\circ\text{C}$ | | | 60 | A |
| Pulse Diode Forward Current ^a | I_{SM} | | | | 100 | |
| Body Diode Voltage | V_{SD} | $I_S = 5\text{ A}$ | | 0.76 | 1.1 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F = 20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$ | | 56 | 100 | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | | 65 | 120 | nC |
| Reverse Recovery Fall Time | t_a | | | 22 | | ns |
| Reverse Recovery Rise Time | t_b | | | 34 | | |

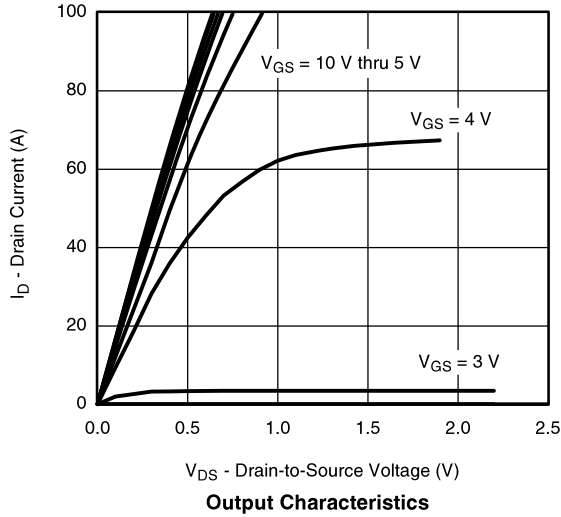
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

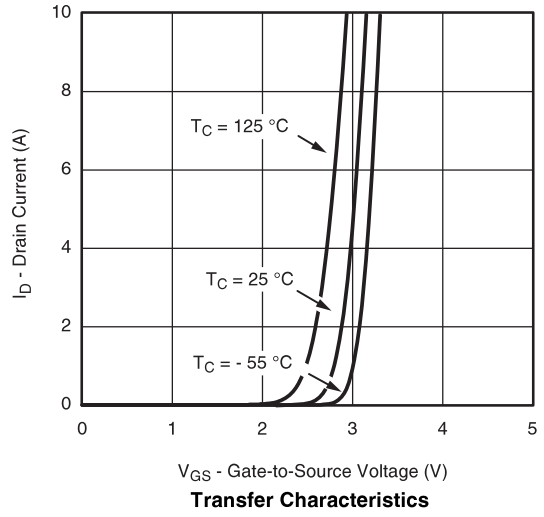
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

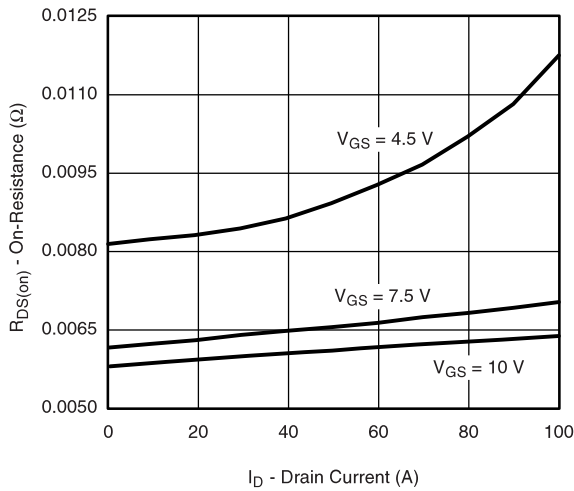
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



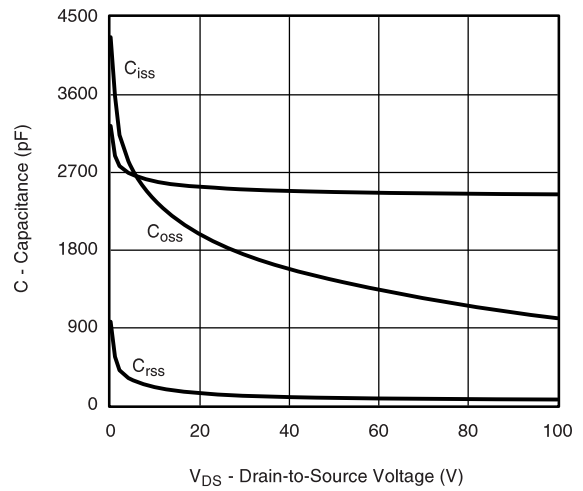
Output Characteristics



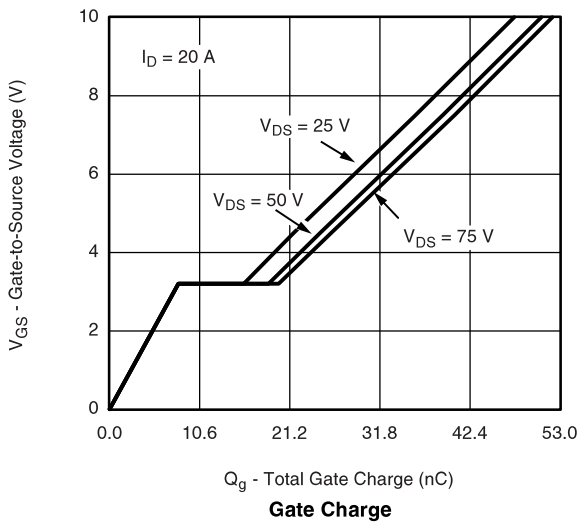
Transfer Characteristics



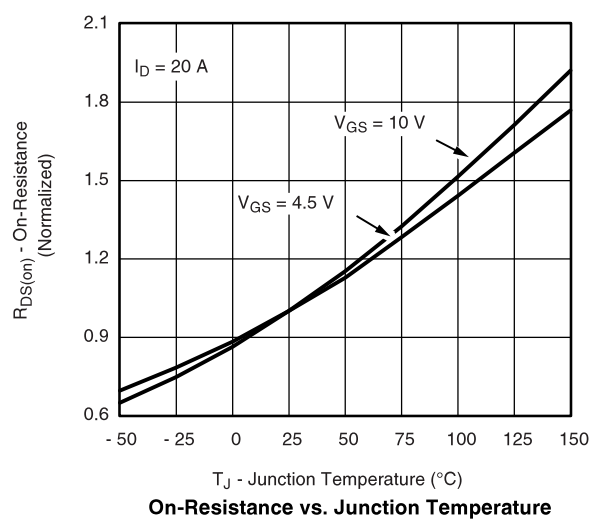
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

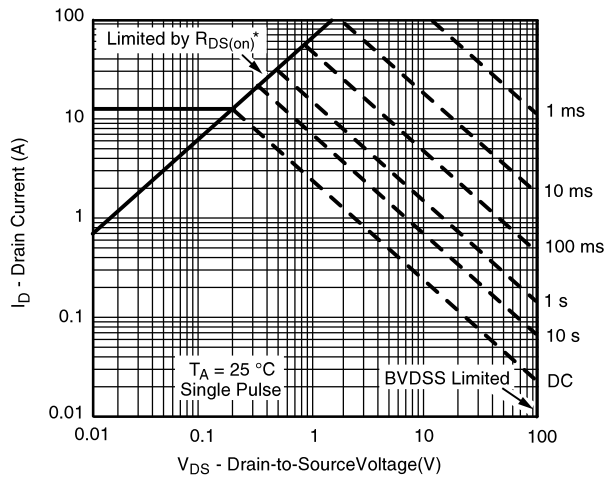
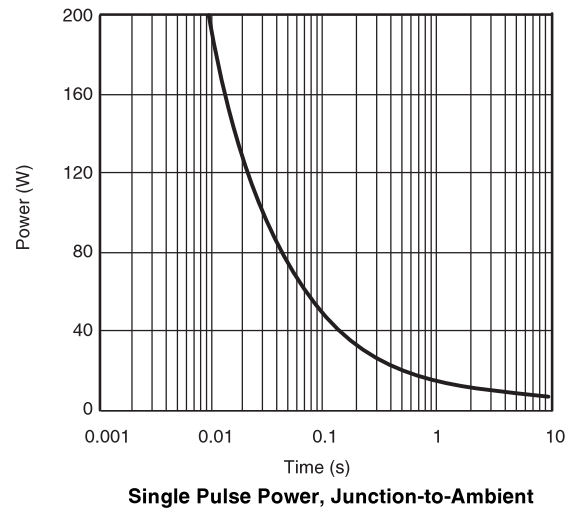
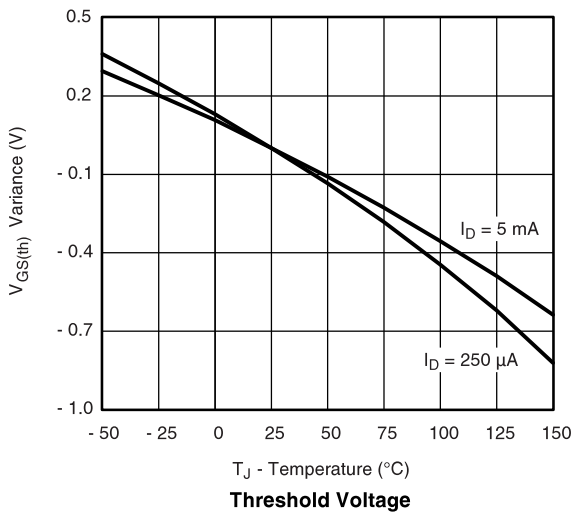
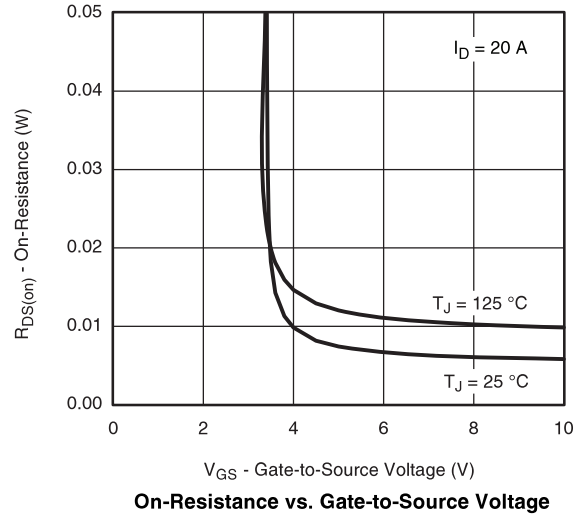
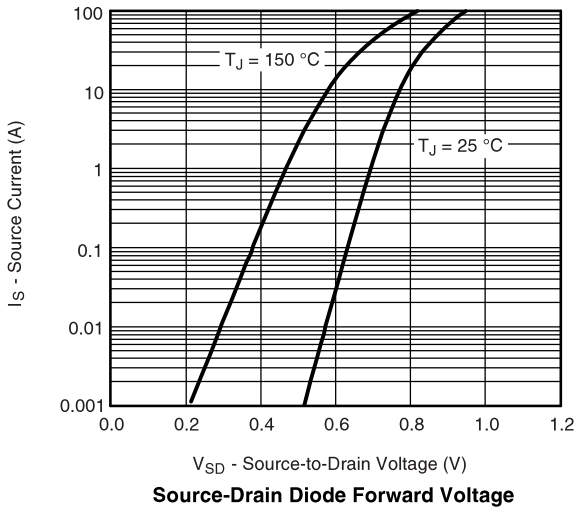


Gate Charge



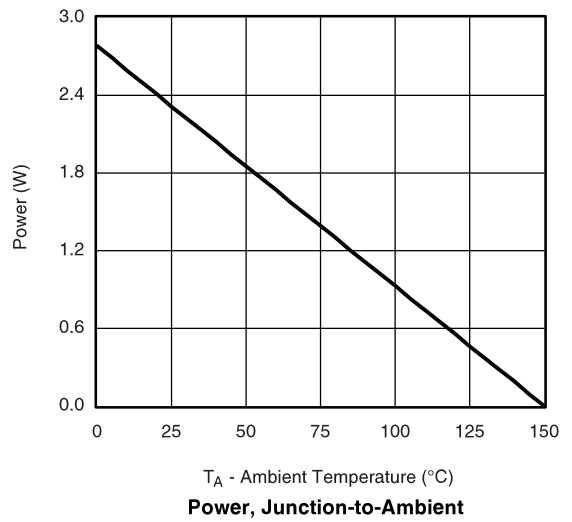
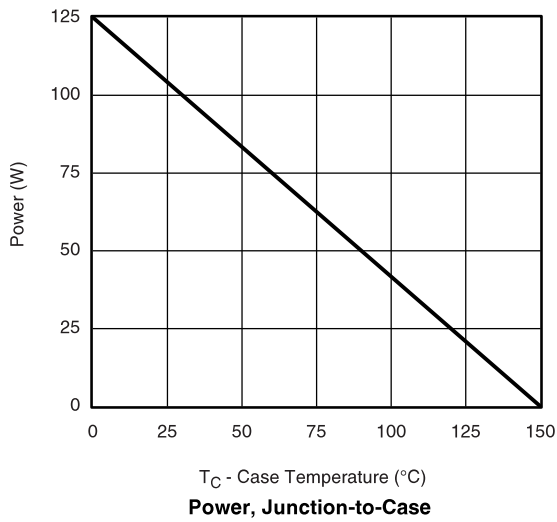
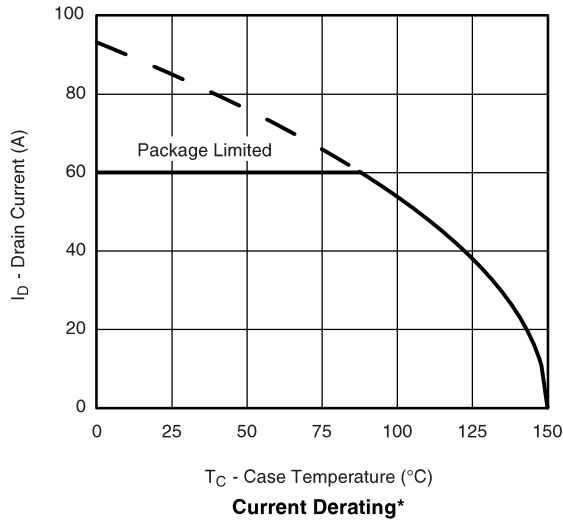
On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

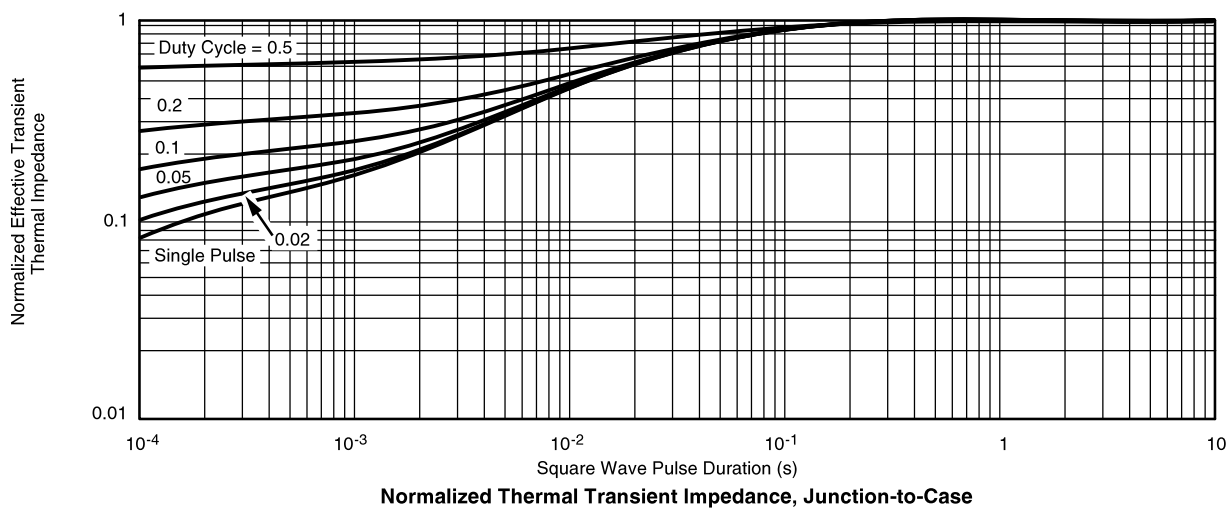
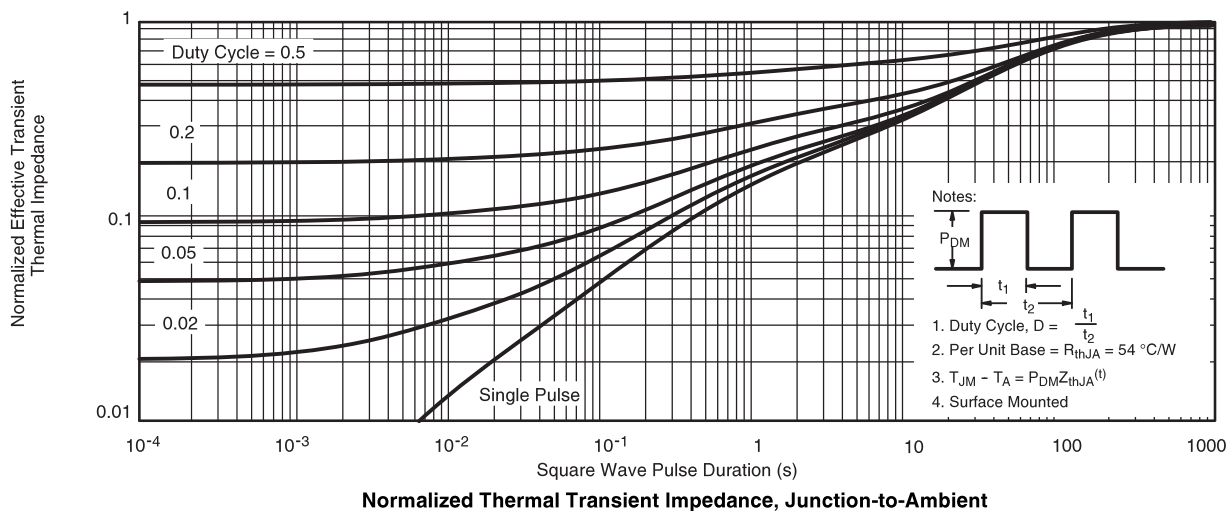


* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

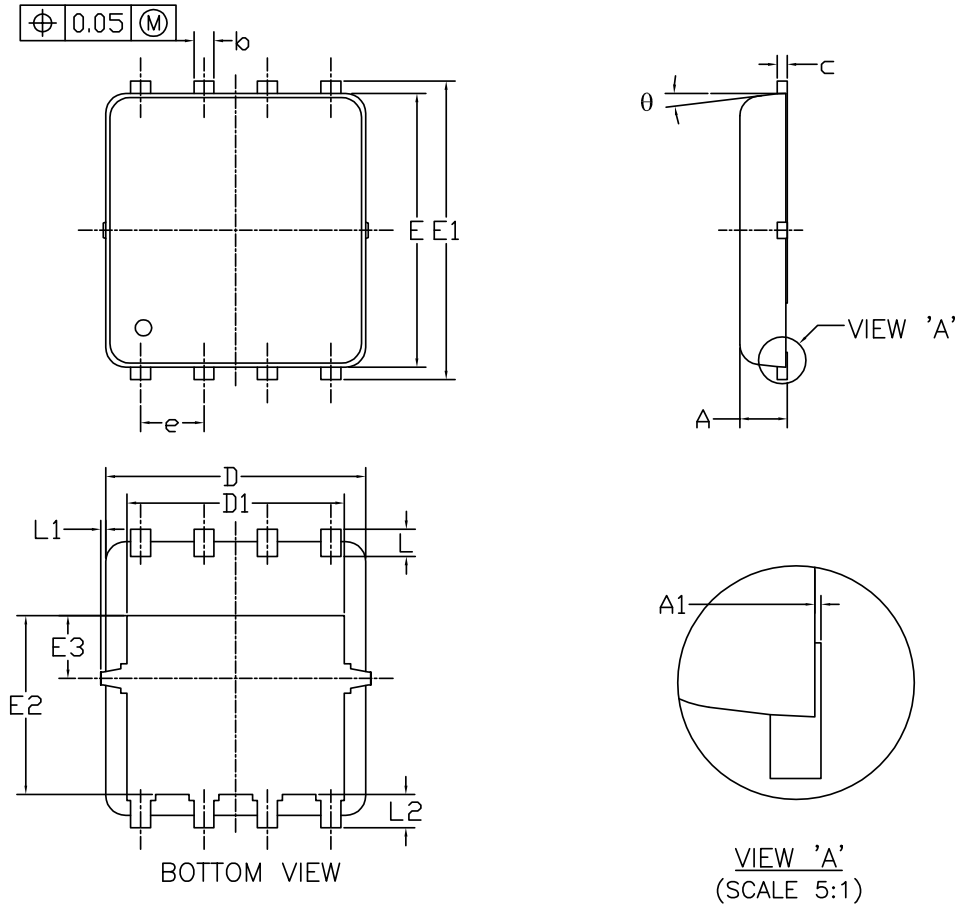
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



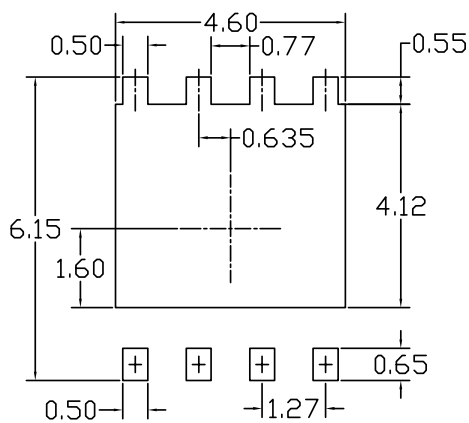
* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



DFN5x6_8L_EP1_P PACKAGE OUTLIN



RECOMMENDED LAND PATTERN



| SYMBOLS | DIMENSIONS IN MILLIMETERS | | | DIMENSIONS IN INCHES | | |
|----------|---------------------------|-------|-------|----------------------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.85 | 0.95 | 1.00 | 0.033 | 0.037 | 0.039 |
| A1 | 0.00 | --- | 0.05 | 0.000 | --- | 0.002 |
| b | 0.30 | 0.40 | 0.50 | 0.012 | 0.016 | 0.020 |
| c | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| D | 5.10 | 5.20 | 5.30 | 0.201 | 0.205 | 0.209 |
| D1 | 4.25 | 4.35 | 4.45 | 0.167 | 0.171 | 0.175 |
| E | 5.45 | 5.55 | 5.65 | 0.215 | 0.219 | 0.222 |
| E1 | 5.95 | 6.05 | 6.15 | 0.234 | 0.238 | 0.242 |
| E2 | 3.525 | 3.625 | 3.725 | 0.139 | 0.143 | 0.147 |
| E3 | 1.175 | 1.275 | 1.375 | 0.046 | 0.050 | 0.054 |
| e | 1.27 BSC | | | 0.050 BSC | | |
| L | 0.45 | 0.55 | 0.65 | 0.018 | 0.022 | 0.026 |
| L1 | 0 | --- | 0.15 | 0 | --- | 0.006 |
| L2 | 0.68 REF | | | 0.027 REF | | |
| θ | 0° | --- | 10° | 0° | --- | 10° |

NOTE

- PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

UNIT: mm

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